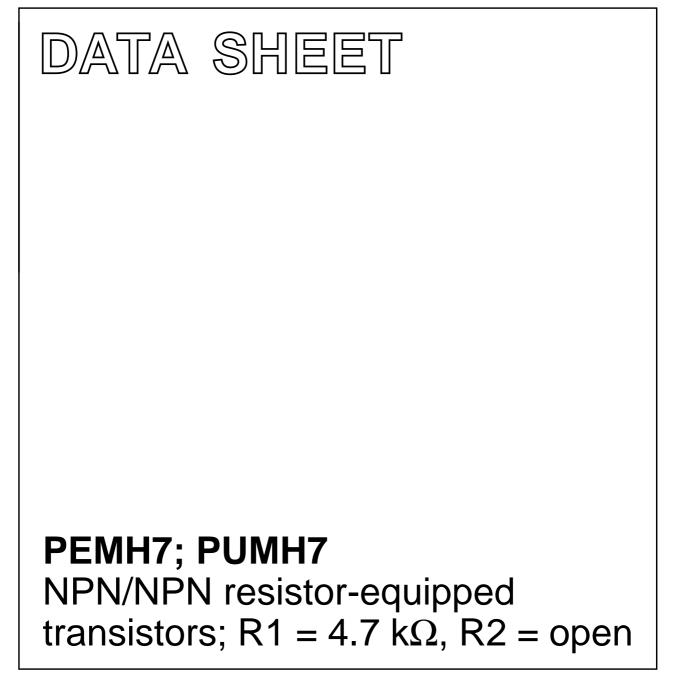
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Oct 22 2003 Oct 02



PEMH7; PUMH7

FEATURES

- Built-in bias resistors
- Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

APPLICATIONS

- Low current peripheral driver
- Replacement of general purpose transistors in digital applications
- Control of IC inputs.

DESCRIPTION

NPN/NPN resistor-equipped transistors (see "Simplified outline, symbol and pinning" for package details).

PRODUCT OVERVIEW

	PACKAGE			NPN/PNP	PNP/PNP	
ITPE NUMBER	PHILIPS	EIAJ		COMPLEMENT	COMPLEMENT	
PEMH7	SOT666	_	H3	PEMD6	PEMB3	
PUMH7	SOT363	SC-88	H*7	PUMD6	PUMB3	

Note

- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL		PINNING		
ITFE NOWBER		PIN	DESCRIPTION		
PEMH7		1	emitter TR1		
PUMH7		2	base TR1		
		3	collector TR2		
		4	emitter TR2		
		5	base TR2		
		6	collector TR1		
	Top view MAM453				

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	-	50	V
lo	output current (DC)	-	100	mA
TR1	NPN	-	_	_
TR2	NPN	-	-	-
R1	bias resistor	4.7	—	kΩ
R2	bias resistor	open	_	_

PEMH7; PUMH7

ORDERING INFORMATION

TYPE NUMBER		PACKAGE			
ITFE NUMBER	NAME	DESCRIPTION	VERSION		
PEMH7	 Plastic surface mounted package; 6 leads 		SOT666		
PUMH7	 Plastic surface mounted package; 6 leads 		SOT363		

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
Per transist	or		!		
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	_	50	V
V _{EBO}	emitter-base voltage	open collector	_	5	V
I _O	output current (DC)		—	100	mA
I _{CM}	peak collector current		_	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT363	note 1	_	200	mW
	SOT666	notes 1 and 2	_	200	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C
Per device	•		ł		•
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT363	note 1	_	300	mW
	SOT666	notes 1 and 2	-	300	mW

Notes

- 1. Device mounted on an FR4 printed-circuit board, single-sided copper, standard footprint.
- 2. Reflow soldering is the only recommended soldering method.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
Per transist	or	•		
R _{th j-a}	thermal resistance from junction to ambient	T _{amb} ≤ 25 °C		
	SOT363	note 1	625	K/W
	SOT666	notes 1 and 2	625	K/W
Per device			•	
R _{th j-a}	thermal resistance from junction to ambient	$T_{amb} \le 25 \ ^{\circ}C$		
	SOT363	note 1	416	K/W
	SOT666	notes 1 and 2	416	K/W

Notes

1. Device mounted on an FR4 printed-circuit board, single-sided copper, standard footprint.

2. Reflow soldering is the only recommended soldering method.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

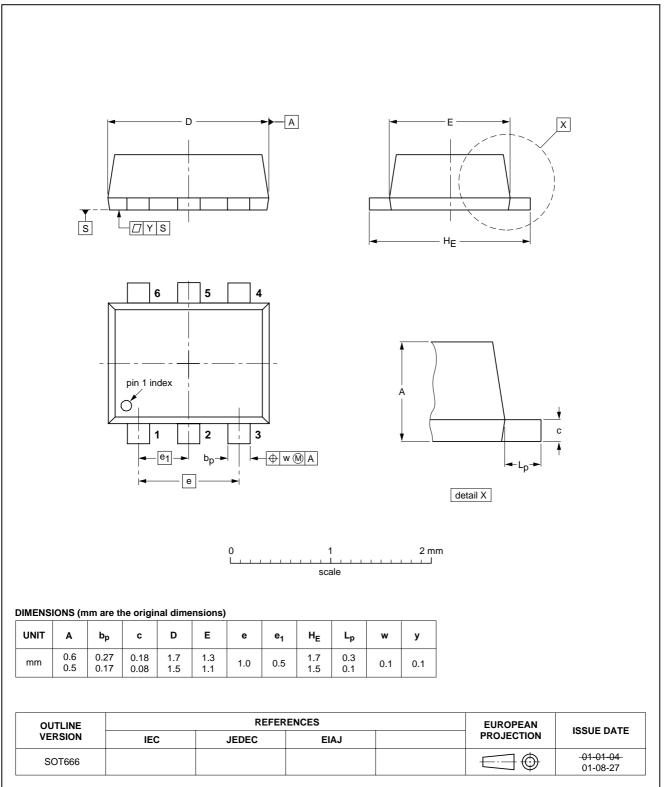
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT		
Per transis	Per transistor							
I _{CBO}	collector-base cut-off current	$V_{CB} = 50 \text{ V}; \text{ I}_{E} = 0$	-	-	100	nA		
I _{CEO}	collector-emitter cut-off current	$V_{CE} = 30 \text{ V}; \text{ I}_{B} = 0$	-	-	1	μA		
		$V_{CE} = 30 \text{ V}; \text{ I}_{B} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$	-	-	50	μA		
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 V; I_{C} = 0$	-	-	100	nA		
h _{FE}	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 1 \text{ mA}$	200	330	-			
V _{CEsat}	collector-emitter saturation voltage	$I_{\rm C} = 5 \text{ mA}; I_{\rm B} = 0.25 \text{ mA}$	-	-	100	mV		
R1	input resistor		3.3	4.7	6.1	kΩ		
Cc	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = i_e = 0; f = 1 \text{ MHz}$	_	_	2.5	pF		

PEMH7; PUMH7

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

PACKAGE OUTLINE

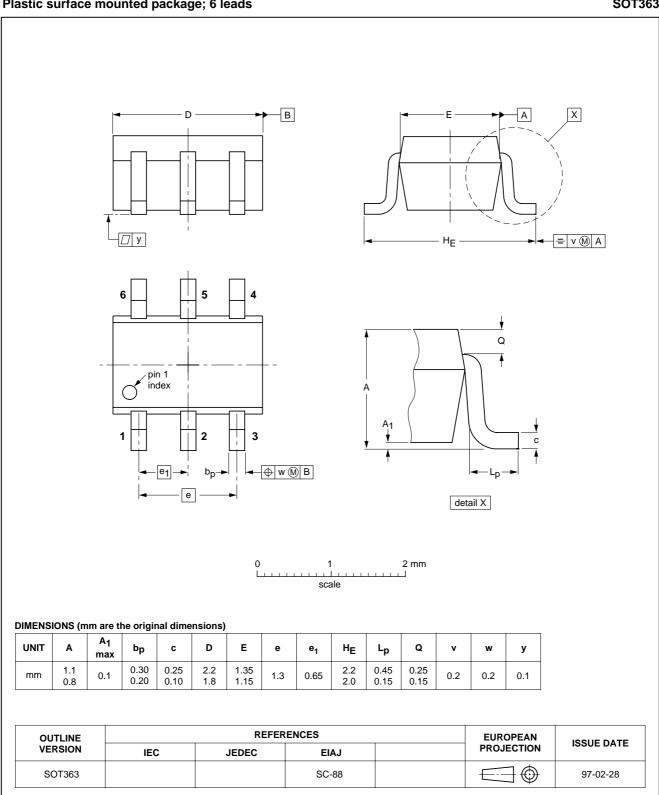
Plastic surface mounted package; 6 leads



SOT666

NPN/NPN resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$, R2 = open

PEMH7; PUMH7



Plastic surface mounted package; 6 leads

SOT363

PEMH7; PUMH7

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
11	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Printed in The Netherlands

R75/03/pp8

Date of release: 2003 Oct 02

Document order number: 9397 750 11873

SCA75

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